# PRODUCT DATA SHEET Indium10.8HF Pb-Free Solder Paste

#### Introduction

Indium10.8HF is an air reflow, no-clean solder paste specifically formulated to accommodate the higher processing temperatures required by the SnAgCu, SnAg, and other alloy systems favored by the electronics industry to replace conventional Pb-bearing solders. Indium10.8HF offers unprecedented stencil print transfer efficiency to work in the broadest range of processes.

#### **Features**

- Excellent NWO performance
- · Very wide reflow profile window under both air and nitrogen
- Excellent HIP performance
- Excellent soldering performance and process yield
  - Excellent wetting to all fresh and aged surface finishes, including, but not limited to:
    - OSP
    - · Immersion Ag
    - Immersion Sn
    - ENIG
  - Low-bridging, tombstoning, and solder beading
  - Low-voiding in all joints including QFN and BGA assemblies
- · Clear post-reflow residue

# **Alloys**

Indium Corporation manufactures low-oxide spherical powder composed of a variety of Pb-free alloys that cover a broad range of melting temperatures. Type 3, Type 4, and Type 5 powders are standard offerings with Pb-free alloys. The metal percent is the weight percent of the solder powder in the solder paste and is dependent upon the powder type and application. Standard product offerings are detailed in the specifications table.

#### **J-STD Tests and Results**

Indium10.8HF Industry Standard Test Results and Classification				
Flux Classification	ROL0	Typical Solder Paste Viscosity for Type 4/4.5 Solder	1,400kcps	
Based on the testing required by IPC J-STD-004B (IPC-TM-650)				
Halogen-free per IEC 61249-2-21, Test Method EN14582	<900ppm CI <900ppm Br <1,500ppm Total	Conforms with all requirements from J-STD-005 (IPC-TM-650)		

All information is for reference only.

Not to be used as incoming product specifications.

# From One Engineer To Another

# **Standard Product Specifications**

Alloy		Metal Load	
Name	Composition	Type 4/4.5	Type 5/T5-MC
SAC387	95.5Sn/3.8Ag/0.7Cu		00 0 00 50/
SAC305	96.5Sn/3.0Ag/0.5Cu	0.00/	
SAC105	98.5Sn/1.0Ag/0.5Cu	89% 88.0-88.5%	
SAC0307	99Sn/0.3Ag/0.7Cu		

# **Compatible Products**

• Rework Flux: TACFlux® 020B, TACFlux® 089HF

Cored Wire: CW-807

• Wave Flux: WF-9945, WF-9958

# **Storage and Handling Procedures**

Refrigerated storage will prolong the shelf life of solder paste. Solder paste packaged in syringes and cartridges should be stored tip down.

Packaging	Storage Conditions (unopened containers)	Shelf Life
Syringe	<-10°C	6 months
Jar/Cartridge	<10°C	6 months

Solder paste should be allowed to reach ambient working temperature prior to use. Generally, paste should be removed from refrigeration at least 2 hours before use. Actual time to reach thermal equilibrium will vary with container size. Paste temperature should be verified before use. Jars and cartridges should be labeled with date and time of opening.

# **Packaging**

**Indium10.8HF** is currently available in 500g jars or 600g cartridges. Packaging for enclosed print head systems is also readily available. Alternate packaging options may be available upon request.



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# **Printing**

#### Stencil Design:

Electroformed and laser cut/electropolished stencils produce the best printing characteristics among stencil types. Stencil aperture design is a crucial step in optimizing the print process. The following are a few general recommendations:

- Discrete components—A 10-20% reduction of stencil aperture has significantly reduced or eliminated the occurrence of mid-chip solder beads. The "home plate" design is a common method for achieving this reduction.
- Fine-pitch components—A surface area reduction is recommended for apertures of 20mil pitch and finer. This reduction will help minimize solder balling and bridging that can lead to electrical shorts. The amount of reduction necessary is process-dependent (5–15% is common).
- For optimum transfer efficiency and release of the solder paste from the stencil apertures, industry standard aperture and aspect ratios should be adhered to.

Printer Operation			
Solder Paste Bead Size	~20-25mm in diameter		
Print Speed	25-150mm/second		
Squeegee Pressure	0.018-0.027kg/mm of blade length		
Underside Stencil Wipe	Start at once per every 5 prints and decrease frequency until optimum value is reached		
Squeegee Type/Angle	Metal with appropriate length/~60 degrees		
Separation Speed	5–20mm/second or per equipment manufacturer's specifications		
Solder Paste Stencil Life	ncil Life Up to 12 hours (at 30–60% RH and 22–28°C)		

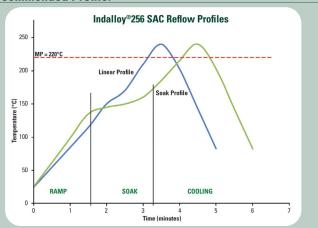
# Cleaning

Indium10.8HF is designed for no-clean applications; however, the flux can be removed, if necessary, by using a commercially available flux residue remover.

Stencil Cleaning is best performed using isopropyl alcohol (IPA) as a solvent. Most commercially available non-water-based stencil cleaners work well.

#### Reflow

#### **Recommended Profile:**



The stated profile recommendations apply to most Pb-free alloys in the SnAgCu (SAC) alloy system, including SAC305 (96.5Sn/3.0Ag/0.5Cu). This can be used as a general guideline in establishing a reflow profile when using **Indium10.8HF** Solder Paste. Deviations from these recommendations are acceptable, and may be necessary, based on specific process requirements, including board size, thickness, and density. Start with the linear profile, then move to the optional soak profile, if needed. The flat soak portion of the linear profile (linear shoulder) may also be eliminated.

Reflow Profile Details	SAC305 Parameters		Comments	
Reliow Frome Details	Recommended	Acceptable	Comments	
Ramp Profile (Average Ambient to Peak)— Not the Same as Maximum Rising Slope	1.0-1.5°C/second	0.5-2.5°C/second	To minimize solder balling, beading, hot slump	
Soak Zone Profile (optional)	20-60 seconds	30–120 seconds	May minimize BGA/CSP voiding Eliminating/reducing the soak zone <u>may</u> help to reduce HIP and graping	
	140-160°C	140-170°C		
Time Above Liquidus (TAL)	45-60 seconds	30-100 seconds	Needed for good wetting/reliable solder joint As measured with thermocouple	
Peak Temperature	230-260°C	230-262°C		
Cooling Ramp Rate	2-6°C/second	0.5-6°C/second	Rapid cooling promotes fine-grain structure	
Reflow Atmosphere	Air or N <sub>2</sub>		N <sub>2</sub> preferred for small components	

All parameters are for reference only.

Modifications may be required to fit process and design.

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All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company,

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